



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-07-13
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDA17P100-1U2M	8096*6TAP17A	A	Z6HA	2016-07-13
	Amount	UoM	Unit type	ST ECOPACK Grade
	6.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2.0x1.80x0.55	6	No lead	
Comment	Package: DFN.20.18.06-040-6L-E			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8096*GTAP17A					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.831	mg	supplier	die	Silicon (Si)	7440-21-3		0.665	mg	800241	110833
				supplier	metallization	Aluminium (Al)	7429-90-5		0.143	mg	172082	23833
				supplier	Passivation	Silicon Oxide	7631-86-9		0.012	mg	14440	2000
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	1203	167
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	2407	333
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.008	mg	9627	1333
Leadframe	Copper and its alloy	1.646	mg	supplier	Alloy	Silicium (Si)	7440-21-3		0.011	mg	6683	1833
				supplier	Alloy	Magnesium (Mg)	7439-95-4		0.002	mg	1215	336
				supplier	Alloy	Copper (Cu)	7440-50-8		1.586	mg	963548	264333
				supplier	Alloy	Nickel (Ni)	7440-02-0		0.045	mg	27339	7500
				supplier	Alloy	Palladium (Pd)	7440-05-3		0.002	mg	1215	333
Die attach	Other organic materials	0.294	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.264	mg	897960	44000
				supplier	glue or tape	Modified Epoxy Resin	Proprietary		0.006	mg	20408	1000
				supplier	glue or tape	2-(2-ethoxyethoxy)ethyl acetate	112-15-2		0.006	mg	20408	1000
				supplier	glue or tape	CP formaldehyde&aniline,maleated	Proprietary		0.003	mg	10204	500
				supplier	glue or tape	Carbonic Ester	Proprietary		0.003	mg	10204	500
				supplier	glue or tape	Acrylic resin	Proprietary		0.006	mg	20408	1000
Bonding wires	Other inorganic materials	0.029	mg	supplier	wire	Epoxy resin	25068-38-6		0.006	mg	20408	1000
				supplier	wire	Copper (Cu)	7440-50-8		0.029	mg	1000000	4833
Encapsulation	Other organic materials	3.200	mg	supplier	mold compound	Epoxy resin	25068-38-6		0.096	mg	30000	16000
				supplier	mold compound	Phenol resin	29690-82-2		0.096	mg	30000	16000
				supplier	mold compound	Silica (Amorphous) A	60676-86-0		2.568	mg	802500	428000
				supplier	mold compound	Silica (Amorphous) B	7631-86-9		0.432	mg	135000	72000
				supplier	mold compound	Carbon Black	1333-86-4		0.008	mg	2500	1333